

(1,00mm) .03937"
FSI SERIES

ELEVATED ONE PIECE INTERFACES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?FSI

Insulator Material:
 Liquid Crystal
 Polymer



Contact Material:
 BeCu

Current Rating:
 1A @ 80°C ambient
Operating Temp Range:
 -55°C to +125°C

Plating:
 Au or Sn over
 50µ" (1,27µm) Ni

Processing:

Max Processing Temp:
 230°C for 60 seconds, or
 260°C for 20 seconds 3x
Lead-Free Solderable:
 Yes

SMT Lead Coplanarity:
 (0,10mm) .004" max (05-35)
 (0,15mm) .006" max (40-50)

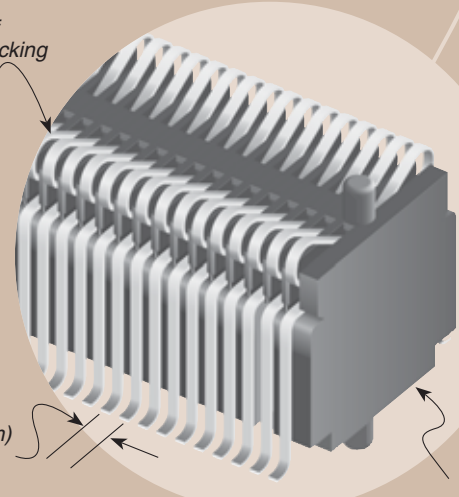
Compression Board:
 Gold Pads required

APPLICATION SPECIFIC OPTION
 Metric insert, no alignment pin, top side alignment pin and bottom side alignment pin.
 Call Samtec.

Choice of board stacking profiles

(1,00mm) .03937"

ALSO AVAILABLE
 Low profile see SEI series.
 (2,54mm) .100" pitch see SIB series.



Short version or optional threaded inserts

FSI	1 PINS PER ROW	BODY HEIGHT	PLATING OPTION	D	INSERT OPTION	AD	OTHER OPTION
	10, 20, 30, 40 & 50 (Screw Option) 05, 10, 15, 20, 25, 30, 35, 40, 45, 50 (Short Version)	-06 = 6,00mm -10 = 10,00mm	-L = 10µ" (0,25µm) Gold on contact, Matte Tin on tail		Leave blank for Short Version (No screw down inserts or holes) -E = #2-56 x 1/16" screw thread		-K = (8,00mm) .315" DIA Polyimide Film Pick & Place Pad (40 & 50 position with threaded insert option only) -P = Plastic Pick & Place Pad (5,08mm) .200" x (12,45mm) .490" (40 & 50 not available with -E or -M) -TR = Tape & Reel Packaging

Contact Detail

Insert Option (10, 20 & 30 pins/row)

BODY HEIGHT	B
-06	(6,00) .236
-10	(10,00) .394

Short Version

Insert Option (40 & 50 pins/row)

Note: Applications requiring 40-50 positions without threaded inserts, please contact Samtec Interconnect Processing Group.

Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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